

## Power MOSFET

### PRODUCT SUMMARY

|                           |                 |      |
|---------------------------|-----------------|------|
| $V_{DS}$ (V)              | 200             |      |
| $R_{DS(on)}$ ( $\Omega$ ) | $V_{GS} = 10$ V | 0.40 |
| $Q_g$ (Max.) (nC)         | 43              |      |
| $Q_{gs}$ (nC)             | 7.0             |      |
| $Q_{gd}$ (nC)             | 23              |      |
| Configuration             | Single          |      |

### FEATURES

- Dynamic  $dV/dt$  Rating
- Repetitive Avalanche Rated
- Fast Switching
- Ease of Paralleling
- Simple Drive Requirements
- Compliant to RoHS Directive 2002/95/EC



Available  
**RoHS\***  
COMPLIANT

### DESCRIPTION

Third generation Power MOSFETs from Vishay provide the designer with the best combination of fast switching, ruggedized device design, low on-resistance and cost-effectiveness.

The TO-220AB package is universally preferred for all commercial-industrial applications at power dissipation levels to approximately 50 W. The low thermal resistance and low package cost of the TO-220AB contribute to its wide acceptance throughout the industry.



### ORDERING INFORMATION

|                |                         |
|----------------|-------------------------|
| Package        | TO-220AB                |
| Lead (Pb)-free | IRF630PbF<br>SiHF630-E3 |
| SnPb           | IRF630<br>SiHF630       |

### ABSOLUTE MAXIMUM RATINGS ( $T_C = 25^\circ\text{C}$ , unless otherwise noted)

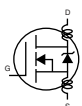

| PARAMETER  | SYMBOL           | LIMIT                     | UNIT                |
|--|------------------|---------------------------|---------------------|
| Drain-Source Voltage                             | $V_{DS}$         | 200                       | V                   |
| Gate-Source Voltage                              | $V_{GS}$         | $\pm 20$                  |                     |
| Continuous Drain Current                         | $I_D$            | $T_C = 25^\circ\text{C}$  | A                   |
|  |                  | $T_C = 100^\circ\text{C}$ |                     |
| Pulsed Drain Current <sup>a</sup>                | $I_{DM}$         | 36                        |                     |
| Linear Derating Factor                           |                  | 0.59                      | W/ $^\circ\text{C}$ |
| Single Pulse Avalanche Energy <sup>b</sup>       | $E_{AS}$         | 250                       | mJ                  |
| Repetitive Avalanche Current <sup>a</sup>        | $I_{AR}$         | 9.0                       | A                   |
| Repetitive Avalanche Energy <sup>a</sup>         | $E_{AR}$         | 7.4                       | mJ                  |
| Maximum Power Dissipation                        | $P_D$            | 74                        | W                   |
| Peak Diode Recovery $dV/dt^c$                    | $dV/dt$          | 5.0                       | V/ns                |
| Operating Junction and Storage Temperature Range | $T_J, T_{stg}$   | - 55 to + 150             | $^\circ\text{C}$    |
| Soldering Recommendations (Peak Temperature)     | for 10 s         | 300 <sup>d</sup>          |                     |
| Mounting Torque                                  | 6-32 or M3 screw | 10                        | lbf · in            |
|  |                  | 1.1                       | N · m               |

#### Notes

- Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).
- $V_{DD} = 50$  V, starting  $T_J = 25^\circ\text{C}$ ,  $L = 4.6$  mH,  $R_g = 25\ \Omega$ ,  $I_{AS} = 9.0$  A (see fig. 12).
- $I_{SD} \leq 9.0$  A,  $dI/dt \leq 120$  A/ $\mu\text{s}$ ,  $V_{DD} \leq V_{DS}$ ,  $T_J \leq 150^\circ\text{C}$ .
- 1.6 mm from case.

\* Pb containing terminations are not RoHS compliant, exemptions may apply

| THERMAL RESISTANCE RATINGS          |            |      |      |      |
|-------------------------------------|------------|------|------|------|
| PARAMETER                           | SYMBOL     | TYP. | MAX. | UNIT |
| Maximum Junction-to-Ambient         | $R_{thJA}$ | -    | 62   | °C/W |
| Case-to-Sink, Flat, Greased Surface | $R_{thCS}$ | 0.50 | -    |      |
| Maximum Junction-to-Case (Drain)    | $R_{thJC}$ | -    | 1.7  |      |

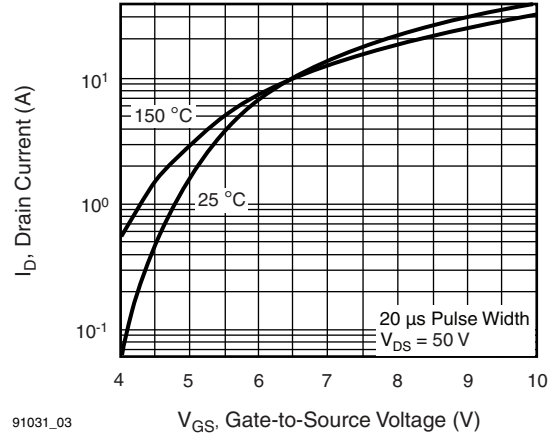
| SPECIFICATIONS ( $T_J = 25\text{ }^\circ\text{C}$ , unless otherwise noted) |                     |  |      |      |           |               |
|---|---------------------|--|------|------|-----------|---------------|
| PARAMETER   | SYMBOL              | TEST CONDITIONS  | MIN. | TYP. | MAX.      | UNIT          |
| <b>Static</b>   |                     |  |      |      |           |               |
| Drain-Source Breakdown Voltage  | $V_{DS}$            | $V_{GS} = 0\text{ V}, I_D = 250\text{ }\mu\text{A}$  | 200  | -    | -         | V             |
| $V_{DS}$ Temperature Coefficient  | $\Delta V_{DS}/T_J$ | Reference to $25\text{ }^\circ\text{C}, I_D = 1\text{ mA}$   | -    | 0.24 | -         | V/°C          |
| Gate-Source Threshold Voltage   | $V_{GS(th)}$        | $V_{DS} = V_{GS}, I_D = 250\text{ }\mu\text{A}$  | 2.0  | -    | 4.0       | V             |
| Gate-Source Leakage   | $I_{GSS}$           | $V_{GS} = \pm 20\text{ V}$   | -    | -    | $\pm 100$ | nA            |
| Zero Gate Voltage Drain Current   | $I_{DSS}$           | $V_{DS} = 200\text{ V}, V_{GS} = 0\text{ V}$   | -    | -    | 25        | $\mu\text{A}$ |
|   |                     | $V_{DS} = 160\text{ V}, V_{GS} = 0\text{ V}, T_J = 125\text{ }^\circ\text{C}$  | -    | -    | 250       |               |
| Drain-Source On-State Resistance  | $R_{DS(on)}$        | $V_{GS} = 10\text{ V}, I_D = 5.4\text{ A}^b$   | -    | -    | 0.40      | $\Omega$      |
| Forward Transconductance  | $g_{fs}$            | $V_{DS} = 50\text{ V}, I_D = 5.4\text{ A}$   | 3.8  | -    | -         | S             |
| <b>Dynamic</b>  |                     |  |      |      |           |               |
| Input Capacitance   | $C_{iss}$           | $V_{GS} = 0\text{ V}, V_{DS} = 25\text{ V}, f = 1.0\text{ MHz}, \text{ see fig. 5}$  | -    | 800  | -         | pF            |
| Output Capacitance  | $C_{oss}$           |  | -    | 240  | -         |               |
| Reverse Transfer Capacitance  | $C_{rss}$           |  | -    | 76   | -         |               |
| Total Gate Charge   | $Q_g$               | $V_{GS} = 10\text{ V}, I_D = 5.9\text{ A}, V_{DS} = 160\text{ V}, \text{ see fig. 6 and 13}^b$   | -    | -    | 43        | nC            |
| Gate-Source Charge  | $Q_{gs}$            |  | -    | -    | 7.0       |               |
| Gate-Drain Charge   | $Q_{gd}$            |  | -    | -    | 23        |               |
| Turn-On Delay Time  | $t_{d(on)}$         | $V_{DD} = 100\text{ V}, I_D = 5.9\text{ A}, R_g = 12\text{ }\Omega, R_D = 16\text{ }\Omega, \text{ see fig. 10}^b$                                     | -    | 9.4  | -         | ns            |
| Rise Time   | $t_r$               |  | -    | 28   | -         |               |
| Turn-Off Delay Time   | $t_{d(off)}$        |  | -    | 39   | -         |               |
| Fall Time   | $t_f$               |  | -    | 20   | -         |               |
| Internal Drain Inductance   | $L_D$               | Between lead, 6 mm (0.25") from package and center of die contact  | -    | 4.5  | -         | nH            |
| Internal Source Inductance  | $L_S$               |  | -    | 7.5  | -         |               |
| <b>Drain-Source Body Diode Characteristics</b>                              |                     |  |      |      |           |               |
| Continuous Source-Drain Diode Current                                       | $I_S$               | MOSFET symbol showing the integral reverse p - n junction diode    | -    | -    | 9.0       | A             |
| Pulsed Diode Forward Current <sup>a</sup>                                   | $I_{SM}$            |  | -    | -    | 36        |               |
| Body Diode Voltage  | $V_{SD}$            | $T_J = 25\text{ }^\circ\text{C}, I_S = 9.0\text{ A}, V_{GS} = 0\text{ V}^b$  | -    | -    | 2.0       | V             |
| Body Diode Reverse Recovery Time  | $t_{rr}$            | $T_J = 25\text{ }^\circ\text{C}, I_F = 5.9\text{ A}, dI/dt = 100\text{ A}/\mu\text{s}$   | -    | 170  | 340       | ns            |
| Body Diode Reverse Recovery Charge  | $Q_{rr}$            |  | -    | 1.1  | 2.2       | nC            |
| Forward Turn-On Time  | $t_{on}$            | Intrinsic turn-on time is negligible (turn-on is dominated by $L_S$ and $L_D$ )  |      |      |           |               |

**Notes**

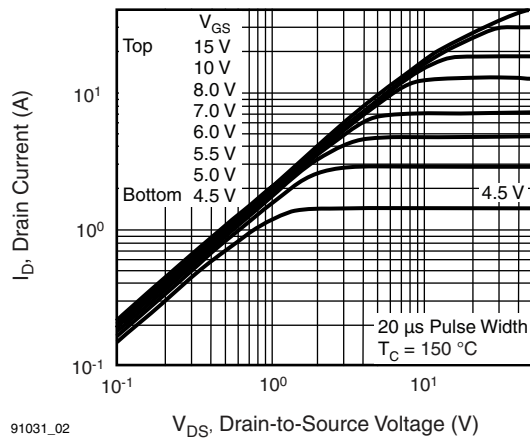
- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).
- b. Pulse width  $\leq 300\text{ }\mu\text{s}$ ; duty cycle  $\leq 2\%$ .

**TYPICAL CHARACTERISTICS** (25 °C, unless otherwise noted)

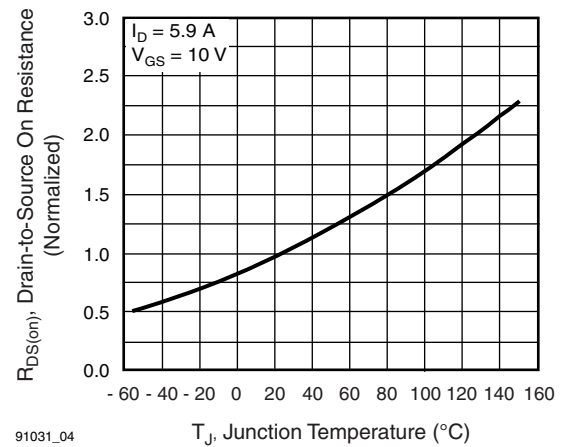

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**Fig. 1 - Typical Output Characteristics,  $T_C = 25\text{ }^\circ\text{C}$** 


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**Fig. 3 - Typical Transfer Characteristics**


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**Fig. 2 - Typical Output Characteristics,  $T_C = 150\text{ }^\circ\text{C}$** 


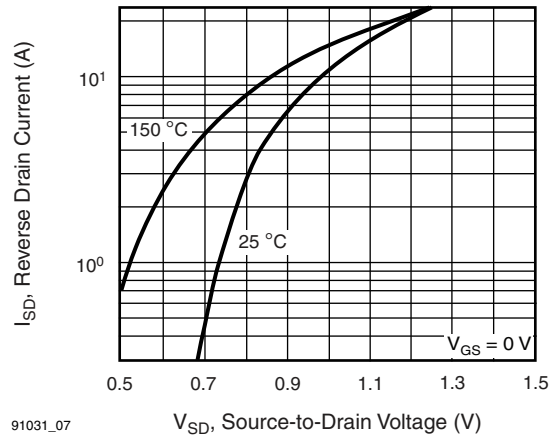
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**Fig. 4 - Normalized On-Resistance vs. Temperature**



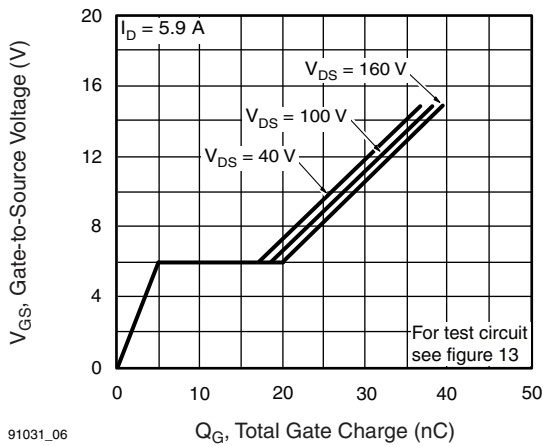
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Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage



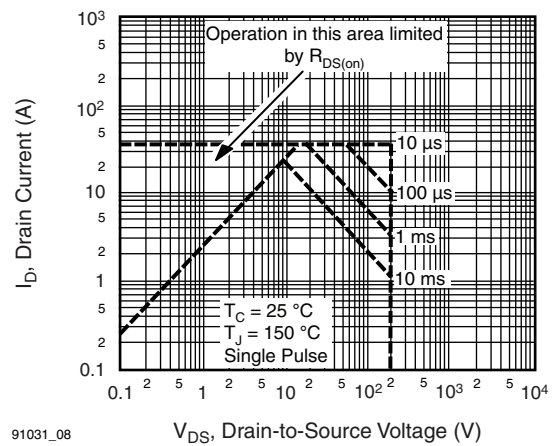
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Fig. 7 - Typical Source-Drain Diode Forward Voltage



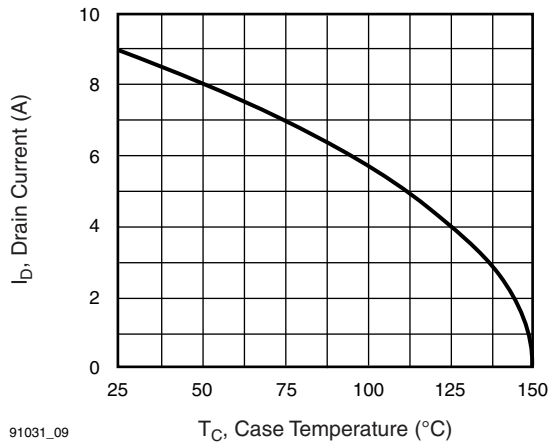
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Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage



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Fig. 8 - Maximum Safe Operating Area



**Fig. 9 - Maximum Drain Current vs. Case Temperature**



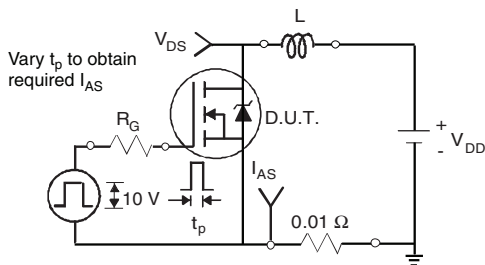
**Fig. 10a - Switching Time Test Circuit**



**Fig. 10b - Switching Time Waveforms**



**Fig. 11 - Maximum Effective Transient Thermal Impedance, Junction-to-Case**



**Fig. 12a - Unclamped Inductive Test Circuit**



**Fig. 12b - Unclamped Inductive Waveforms**

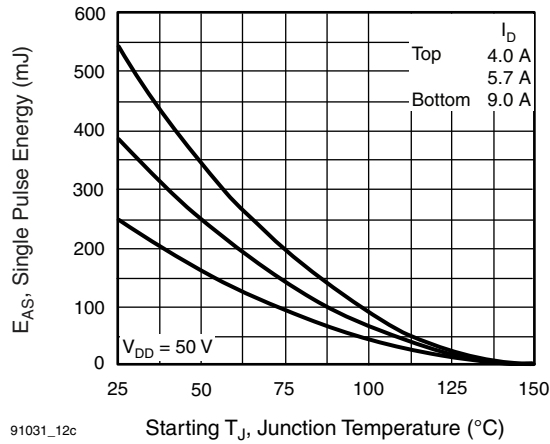


Fig. 12c - Maximum Avalanche Energy vs. Drain Current

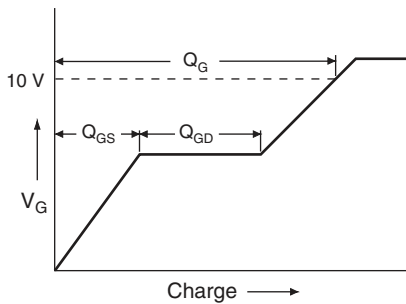


Fig. 13a - Basic Gate Charge Waveform

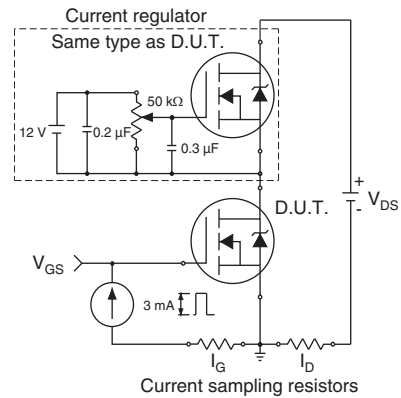


Fig. 13b - Gate Charge Test Circuit


**Note**

 a.  $V_{GS} = 5 V$  for logic level devices

**Fig. 14 - For N-Channel**

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see <http://www.vishay.com/ppg?91031>.



TO-220-1



| DIM. | MILLIMETERS |       | INCHES |       |
|------|-------------|-------|--------|-------|
|      | MIN.        | MAX.  | MIN.   | MAX.  |
| A    | 4.14        | 4.70  | 0.163  | 0.185 |
| b    | 0.69        | 1.02  | 0.027  | 0.040 |
| b(1) | 1.14        | 1.73  | 0.045  | 0.068 |
| c    | 0.36        | 0.61  | 0.014  | 0.024 |
| D    | 14.33       | 15.85 | 0.564  | 0.624 |
| E    | 9.96        | 10.52 | 0.392  | 0.414 |
| e    | 2.41        | 2.67  | 0.095  | 0.105 |
| e(1) | 4.88        | 5.28  | 0.192  | 0.208 |
| F    | 0.43        | 1.40  | 0.017  | 0.055 |
| H(1) | 6.10        | 6.48  | 0.240  | 0.255 |
| J(1) | 2.41        | 2.92  | 0.095  | 0.115 |
| L    | 13.36       | 14.40 | 0.526  | 0.567 |
| L(1) | 3.33        | 4.04  | 0.131  | 0.159 |
| Ø P  | 3.53        | 3.94  | 0.139  | 0.155 |
| Q    | 2.59        | 3.00  | 0.102  | 0.118 |

ECN: X15-0003-Rev. A, 19-Jan-15  
DWG: 6031

Notes

- M\* = 0.052 inches to 0.064 inches (dimension including protrusion), heatsink hole for HVM
- Outline conforms to JEDEC® outline TO-220AB with exception of dimension F





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